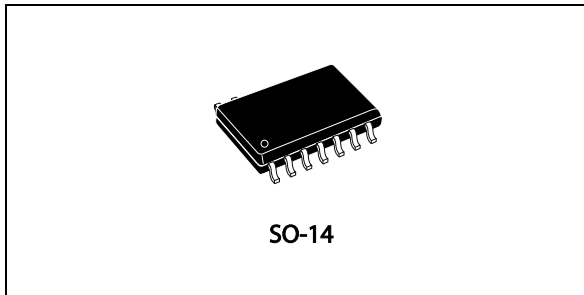


Advanced IGBT/MOSFET driver

Datasheet - production data



Features

- 1.5 A source/2.3 A sink (typ.) gate drive
- Active Miller clamp feature
- Two-level turn-off with adjustable level and delay
- Desaturation detection
- Fault status output
- Negative gate drive capability
- Input compatible with pulse transformer or optocoupler
- Separate sink and source outputs for easy gate driving
- UVLO protection
- 2 kV ESD protection (HBM)

Applications

- 1200 V, 3-phase inverters
- Motor control
- UPS systems

Description

The TD350E device is an advanced gate driver for IGBTs and power MOSFETs. Control and protection functions are included and allow the design of high reliability systems.

The innovative active Miller clamp function eliminates the need for negative gate drive in most applications and allows the use of a simple bootstrap supply for the high side driver.

The device includes a two-level turn-off feature with adjustable level and delay. This function protects against excessive overvoltage at turn-off in case of overcurrent or short-circuit conditions. The same delay set in the two-level turn-off feature is applied at turn-on to prevent pulse width distortion.

The device also includes IGBT desaturation protection and a FAULT status output, and is compatible with both pulse transformer and optocoupler signals.

Table 1. Device summary

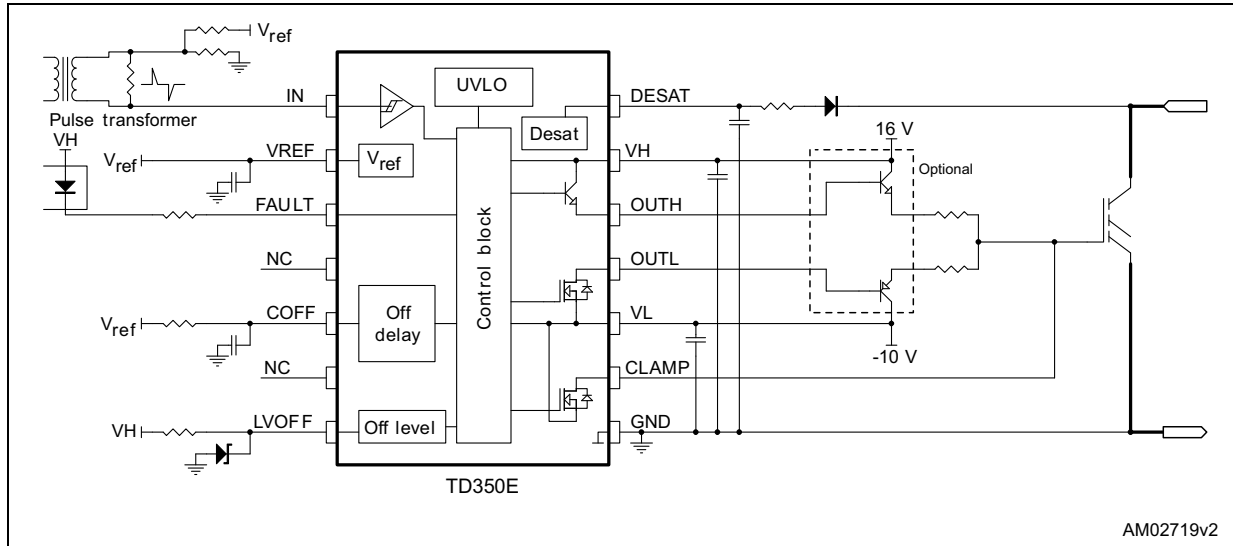
| Order code | Temperature range | Package | Packaging |
|------------|-------------------|---------|---------------|
| TD350E | -40, +125 °C | SO-14 | Tube |
| TD350ETR | | | Tape and reel |

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1 Block diagram

Figure 1. Functional block diagram



2 Pin connections

Figure 2. Pin connections (top view)

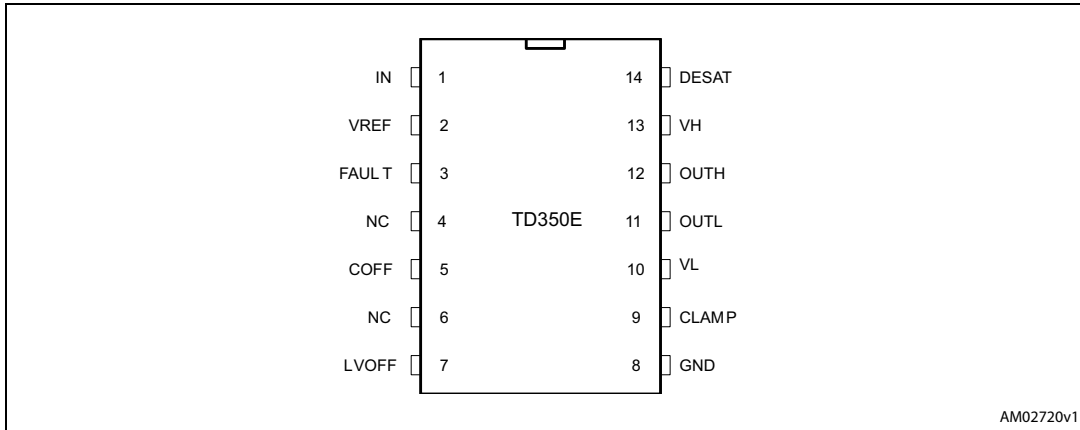


Table 2. Pin description

| Name | Pin number | Type | Function |
|-------|------------|------------------|----------------------------|
| IN | 1 | Analog input | Input |
| VREF | 2 | Analog output | +5 V reference voltage |
| FAULT | 3 | Digital output | Fault status output |
| NC | 4 | Not connected | |
| COFF | 5 | Timing capacitor | Turn-off delay |
| NC | 6 | Not connected | |
| LVOFF | 7 | Analog input | Turn-off level |
| GND | 8 | Power supply | Signal ground |
| CLAMP | 9 | Analog output | Miller clamp |
| VL | 10 | Power supply | Negative supply |
| OUTL | 11 | Analog output | Gate drive output (sink) |
| OUTH | 12 | Analog output | Gate drive output (source) |
| VH | 13 | Power supply | Positive supply |
| DESAT | 14 | Analog input | Desaturation protection |

3 Absolute maximum ratings

Table 3. Key parameters and their absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|--------------------|---|--|------|
| V _H L | Maximum supply voltage (V _H - V _L) | 28 | V |
| V _H | Maximum V _H voltage vs. GND | 28 | V |
| V _L | Minimum V _L voltage vs. GND | -12 | V |
| V _{out} | Voltage on OUTH, OUTL, CLAMP pins | V _L - 0.3 to V _H + 0.3 | V |
| V _{des} | Voltage on DESAT, FAULT, LVOFF pin | -0.3 to V _H + 0.3 | V |
| V _{other} | Voltage on other pins (IN, COFF, VREF) | -0.3 to 7 | V |
| P _d | Power dissipation | 500 | mW |
| T _{stg} | Storage temperature | -55 to 150 | °C |
| T _j | Maximum junction temperature | 150 | °C |
| R _{thja} | Thermal resistance junction-ambient | 125 | °C/W |
| R _{thjc} | Thermal resistance junction-case | 22 | °C/W |
| ESD | Electrostatic discharge (HBM) | 2 | kV |

Table 4. Operating conditions

| Symbol | Parameter | Value | Unit |
|--------------------------------|--------------------------------------|------------|------|
| V _H | Positive supply voltage vs. GND | UVLO to 26 | V |
| V _L | Negative supply voltage vs. GND | 0 to -10 | V |
| V _H -V _L | Maximum total supply voltage | 26 | V |
| T _{oper} | Operating free air temperature range | -40 to 125 | °C |

4 Electrical characteristics

$T_A = -20$ to 125 °C, $V_H = 16$ V, $V_L = -10$ V (unless otherwise specified).

Table 5. Electrical characteristics

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Unit |
|--|---------------------------------|---|--------------|-------|----------------------|----------|
| Input | | | | | | |
| V_{ton} | IN turn-on threshold voltage | | 0.8 | 1.0 | | V |
| V_{toff} | IN turn-off threshold voltage | | | 4.0 | 4.2 | V |
| t_{onmin} | Minimum pulse width | | 100 | 135 | 220 | ns |
| I_{inp} | IN input current | | | | 1 | μ A |
| Voltage reference⁽¹⁾ | | | | | | |
| V_{ref} | Voltage reference | $T = 25$ °C $T_{min} < T < T_{max}$ | 4.85 4.77 | 5.00 | 5.15 5.22 | V V |
| I_{ref} | Maximum output current | | 10 | | | mA |
| Desaturation protection | | | | | | |
| V_{des} | Desaturation threshold | | 6.5 | 7.2 | 7.9 | V |
| I_{des} | Source current | | | 250 | | μ A |
| Fault output | | | | | | |
| t_{fault} | Delay for fault detection | | | | 500 | ns |
| V_{FL} | FAULT low voltage | $I_{FLsink} = 10$ mA | | | 1 | V |
| Clamp | | | | | | |
| V_{tclamp} | CLAMP pin voltage threshold | | | 2.0 | | V |
| V_{CL} | Clamp low voltage | $T = 25$ °C; $I_{CLsink} = 500$ mA $T_{min} < T < T_{max}$; $I_{CLsink} = 500$ mA | | | VL + 2.5 VL + 3.0 | V V |
| Off delay | | | | | | |
| V_{tdel} | Voltage threshold | | 2.35 | 2.50 | 2.65 | V |
| R_{del} | Discharge resistor | $I = 1$ mA | | | 500 | Ω |
| Off levels | | | | | | |
| I_{blvoff} | LVOFF peak input current (sink) | LVOFF = 12 V | | 120 | 200 | μ A |
| V_{iolv} | Offset voltage | LVOFF = 12 V | -0.3 | -0.15 | 0 | V |
| Outputs | | | | | | |
| V_{OL1} | Output low voltage | $I_{osink} = 20$ mA | | | VL + 0.35 | V |
| V_{OL2} | Output low voltage | $T = 25$ °C, $I_{osink} = 200$ mA $T_{min} < T < T_{max}$, $I_{osink} = 200$ mA | | | VL + 1.0 VL + 1.5 | V V |

Table 5. Electrical characteristics (continued)

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Unit |
|------------------------------------|----------------------------------|---|----------|------|----------|------|
| V _{OL3} | Output low voltage | T = 25 °C, I _{osink} = 500 mA | | | VL + 2.5 | V |
| | | T _{min} < T < T _{max} , I _{osink} = 500 mA | | | VL + 3.0 | V |
| V _{OH1} | Output high voltage 1 | I _{osource} = 20 mA | VH - 2.5 | | | V |
| V _{OH2} | Output high voltage 2 | I _{osource} = 200 mA | VH - 3.0 | | | V |
| V _{OH3} | Output high voltage 3 | I _{osource} = 500 mA | VH - 4.0 | | | V |
| t _r | Rise time | C _L = 1 nF, 10% to 90% | | | 130 | ns |
| | | VL = 0 VL = -10 V | | | 175 | ns |
| t _f | Fall time ⁽²⁾ | C _L = 1 nF, 90% to 10% | | | 75 | ns |
| | | VL = 0 VL = -10 V | | | 90 | ns |
| t _{pd_on} | Turn-on propagation delay | 10% output change; T = 25 °C | 400 | 500 | 600 | ns |
| | | 10% output change; T _{min} < T < T _{max} | 350 | | 650 | ns |
| t _{pd_off} | Turn-off propagation delay | 10% output change; T = 25 °C | 350 | 450 | 570 | ns |
| | | 10% output change; T _{min} < T < T _{max} | 300 | | 620 | ns |
| ΔT _w | Input to output pulse distortion | 10% output change | 25 | 50 | 120 | ns |
| Undervoltage lockout (UVLO) | | | | | | |
| UVLOH | UVLO top threshold | | 10 | 11 | 12 | V |
| UVLOL | UVLO bottom threshold | | 9 | 10 | 11 | V |
| V _{hyst} | UVLO hysteresis | UVLOH - UVLOL | 0.5 | 1 | | V |
| Supply current | | | | | | |
| I _{in} | Quiescent current | Output = 0 V, no load | | | 5 | mA |

1. Recommended capacitor range on VREF pin is 10 nF to 100 nF.

2. 2-step turn-off disabled.

5 Functional description

5.1 Input

The input is compatible with optocouplers or pulse transformers. The input is triggered by the signal edge and allows the use of a small-sized, low cost pulse transformer. Input is active low (output is high when input is low) to ease the use of the optocoupler. When driven by a pulse transformer, the input pulse (positive and negative) width must be larger than the minimum pulse width t_{onmin} .

5.2 Voltage reference

A voltage reference is used to create accurate timing for the two-level turn-off with external resistor and capacitor.

5.3 Desaturation protection

Desaturation protection ensures the protection of the IGBT in the event of overcurrent. When the DESAT voltage goes higher than 7 V, the output is driven low (with 2-level turn-off, if applicable). The FAULT output is activated. The FAULT state is exited at the next falling edge of IN input.

A programmable blanking time is used to allow enough time for IGBT saturation. Blanking time is provided by an internal current source and external capacitor.

DESAT input can also be used with an external comparator for overcurrent or overtemperature detection.

5.4 Active Miller clamp

A Miller clamp allows the control of the Miller current during a high dV/dt situation and can eliminate the need for a negative supply voltage.

During turn-off, the gate voltage is monitored and the clamp output is activated when gate voltage goes below 2 V (relative to GND). The clamp voltage is V_L+3 V max. for a Miller current up to 500 mA. The clamp is disabled when the IN input is triggered again.

5.5 Two-level turn-off

The two-level turn-off is used to increase the reliability of the application.

During turn-off, gate voltage can be reduced to a programmable level in order to reduce the IGBT current (in the event of overcurrent). This action prevents both dangerous overvoltage across the IGBT and RBSOA problems, especially at short-circuit turn-off.

The two-level turn-off (T_a) delay is programmable through an external resistor and capacitor for accurate timing (refer to [Equation 1](#)).

Turn-off delay (T_a) is also used to delay the input signal to prevent distortion of input pulse width.

Equation 1

$$T_a [\mu\text{s}] \cong 0.7 \cdot R_{\text{off}} [\text{k}\Omega] \cdot C_{\text{off}} [\text{nF}]$$

5.6 Minimum ON time

In order to ensure the proper operation of the 2-level turn-off function, the input ON time (T_{win}) must be greater than the T_{winmin} value:

Equation 2

$$T_{\text{winmin}} = T_a + 2 \cdot R_{\text{del}} \cdot C_{\text{off}}$$

R_{del} is the internal discharge resistor and C_{off} is the external timing capacitor.

Input signals smaller than T_a are ignored. Input signals larger than T_{winmin} are transmitted to the output stage after the T_a delay with minimum width distortion ($\Delta T_w = T_{\text{wout}} - T_{\text{win}}$).

For an input signal width T_{win} between T_a and T_{winmin} , the output width T_{wout} is reduced below T_{win} (pulse distortion) and the IGBT could be partially turned on. These input signals should be avoided during normal operation.

5.7 Output

The output stage is able to sink 2.3 A and source 1.5 A (typ.) at 25 °C (1.2 A/0.75 A minimum over the full temperature range). Separate sink and source outputs allow independent gate charge and discharge control without an extra external diode.

5.8 Fault status output

Fault output is used to signal a fault event (desaturation, UVLO) to a controller. The fault pin is designed to drive an optocoupler.

5.9 Undervoltage protection

Undervoltage detection protects the application in the event of a low V_H supply voltage (during startup or a fault situation). During undervoltage, the OUTH pin is open and the OUTL pin is driven low (active pull-down for $V_H > 2$ V, passive pull-down for $V_H < 2$ V). Fault output signals the undervoltage state and is reset only when undervoltage state disappears.

Figure 3. Undervoltage protection

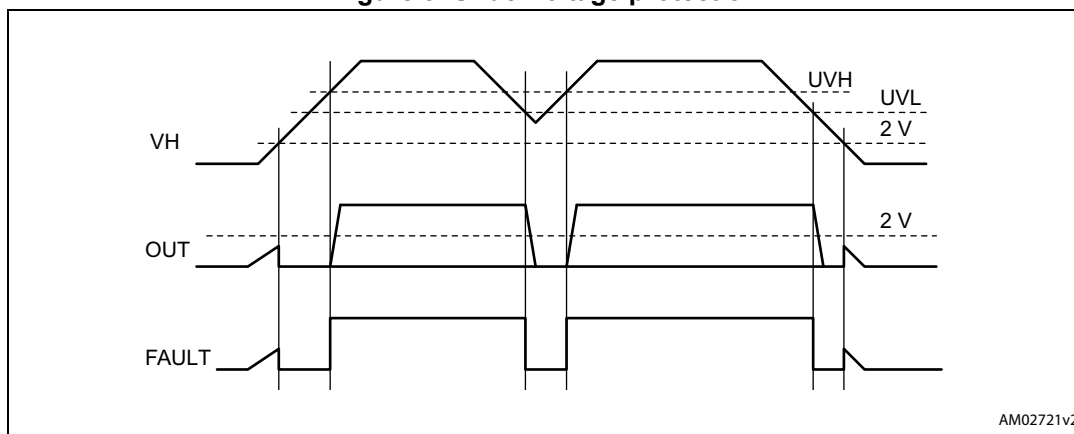
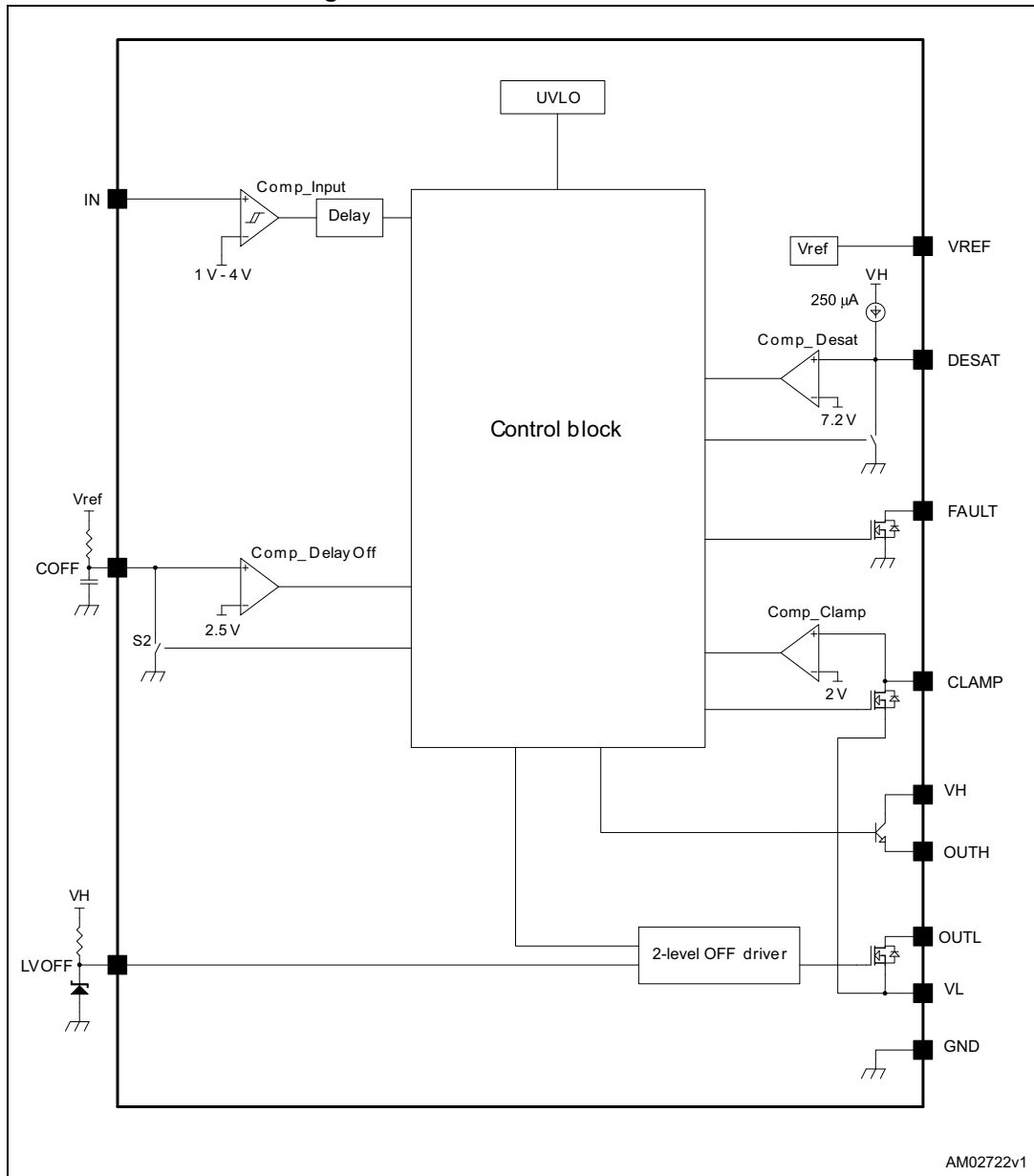


Figure 4. Detailed internal schematic



6 Timing diagrams

Figure 5. Turn-on and turn-off

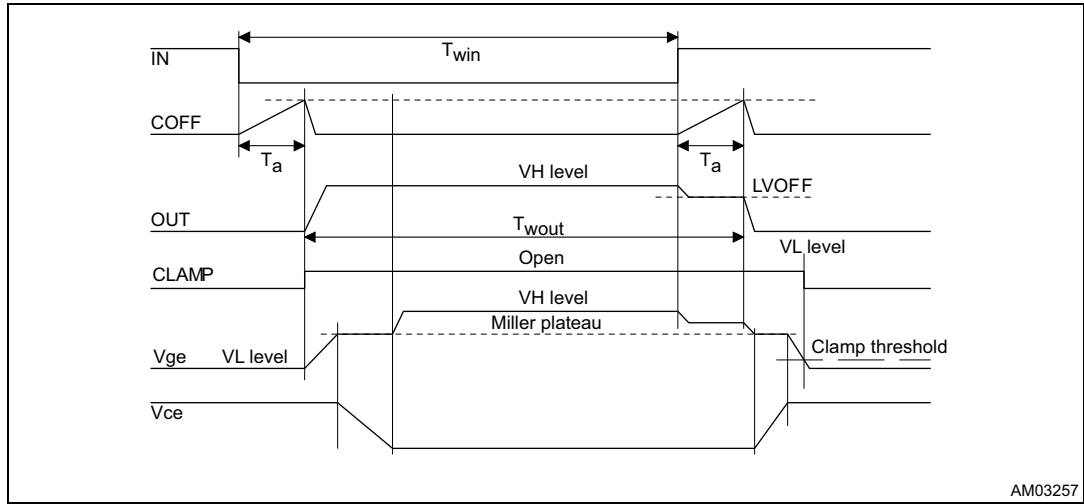


Figure 6. Minimum ON time

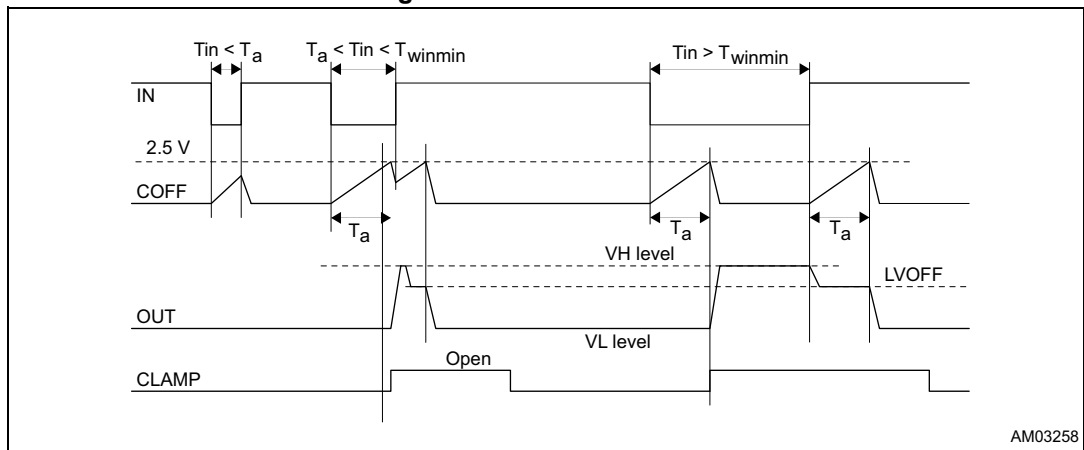
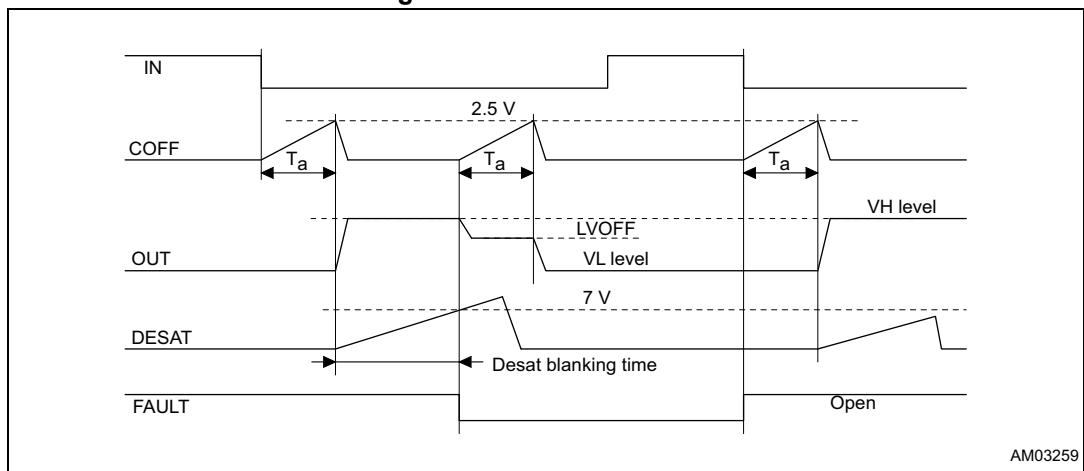


Figure 7. Desaturation fault



7 Typical performance curves

Figure 8. Supply current vs. temperature

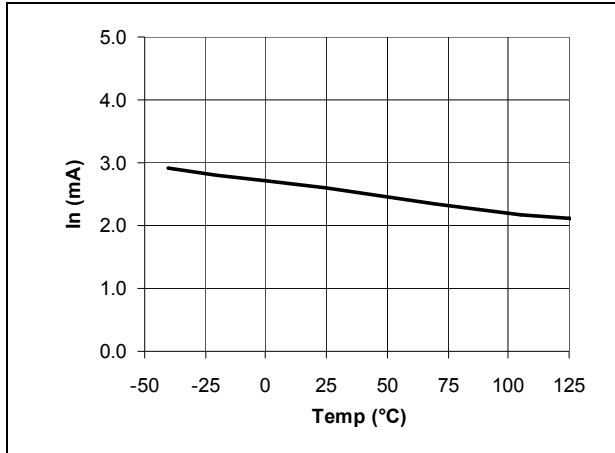


Figure 9. Low level output voltage vs. temp.

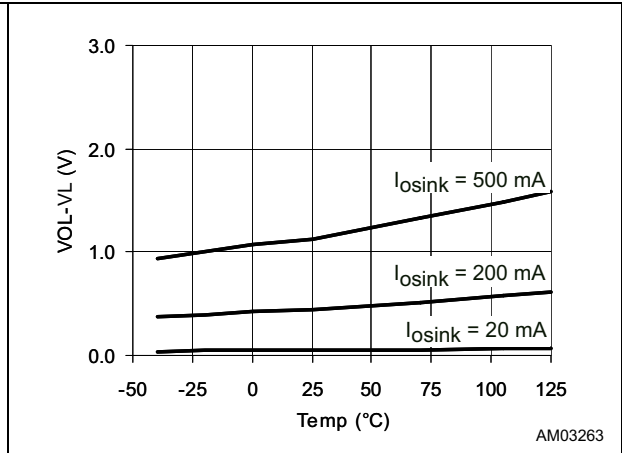


Figure 10. Desaturation threshold vs. temp.

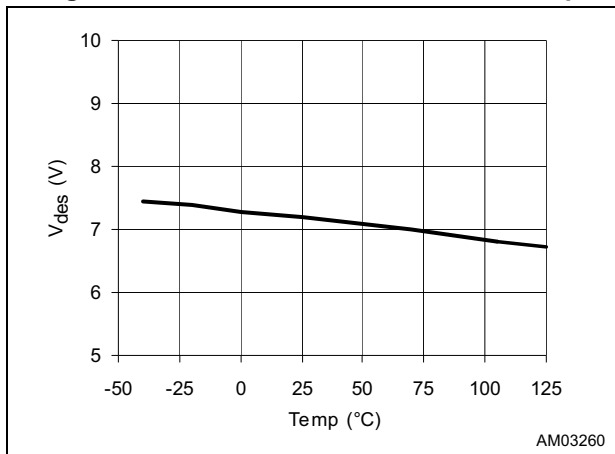


Figure 11. Voltage reference vs. temperature

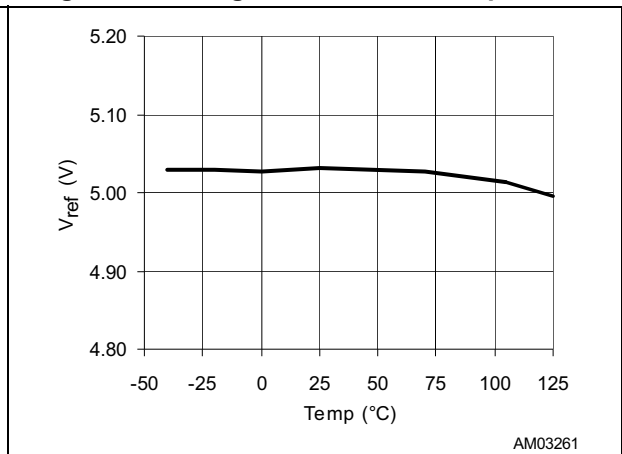


Figure 12. High level output voltage vs. temperature

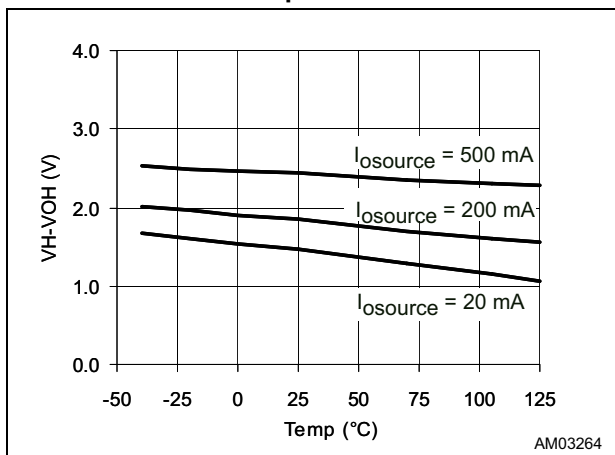
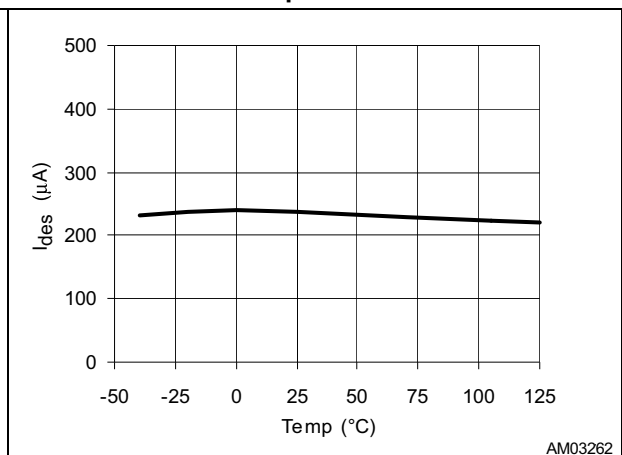


Figure 13. Desaturation source current vs. temperature



8 Application diagrams

Figure 14. Single supply IGBT drive with active Miller clamp and 2-level turn-off

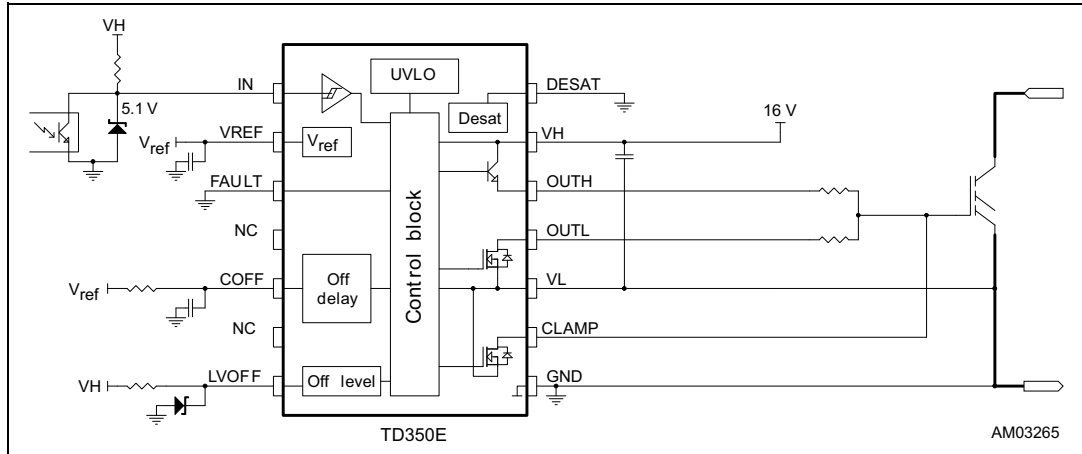


Figure 15. Large IGBT drive with negative gate drive and desaturation detection

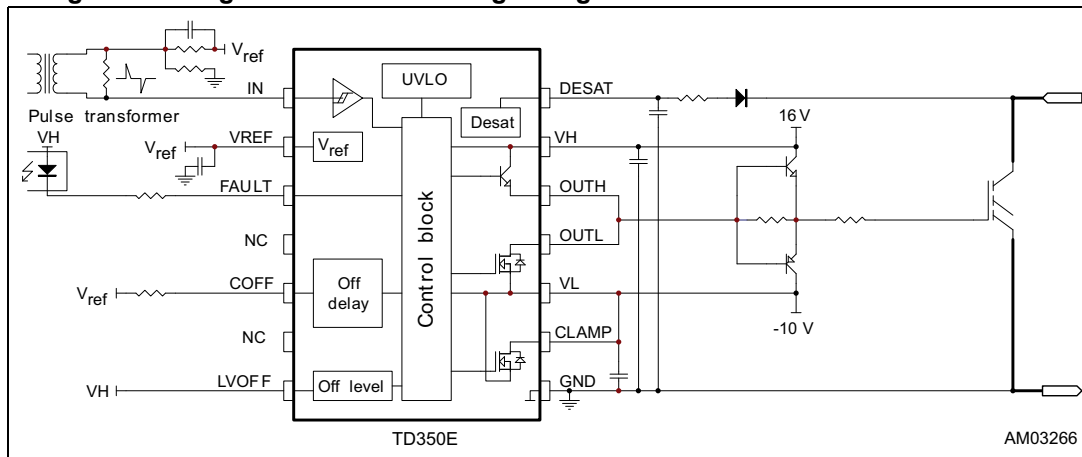
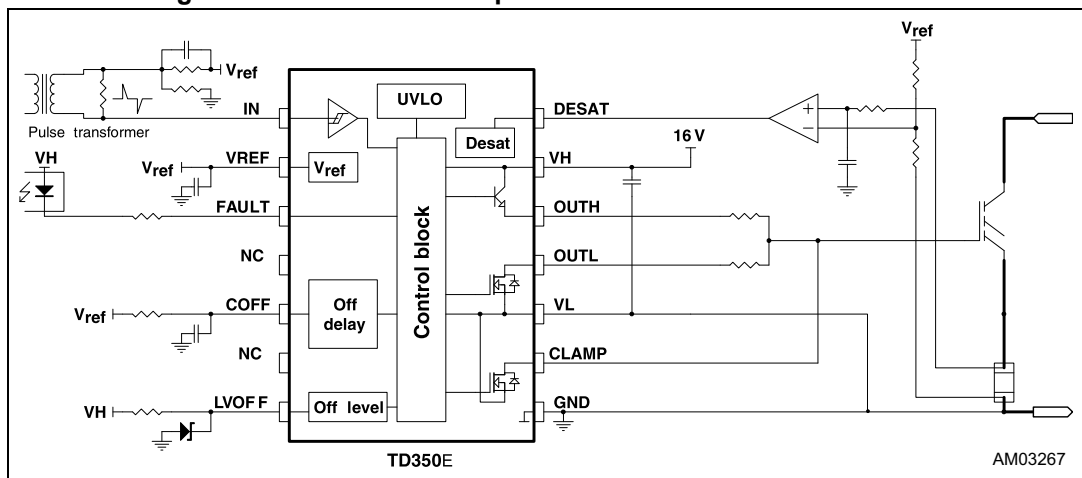


Figure 16. Use of DESAT input for direct overcurrent detection



9 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Figure 17. Package SO-14 package outline

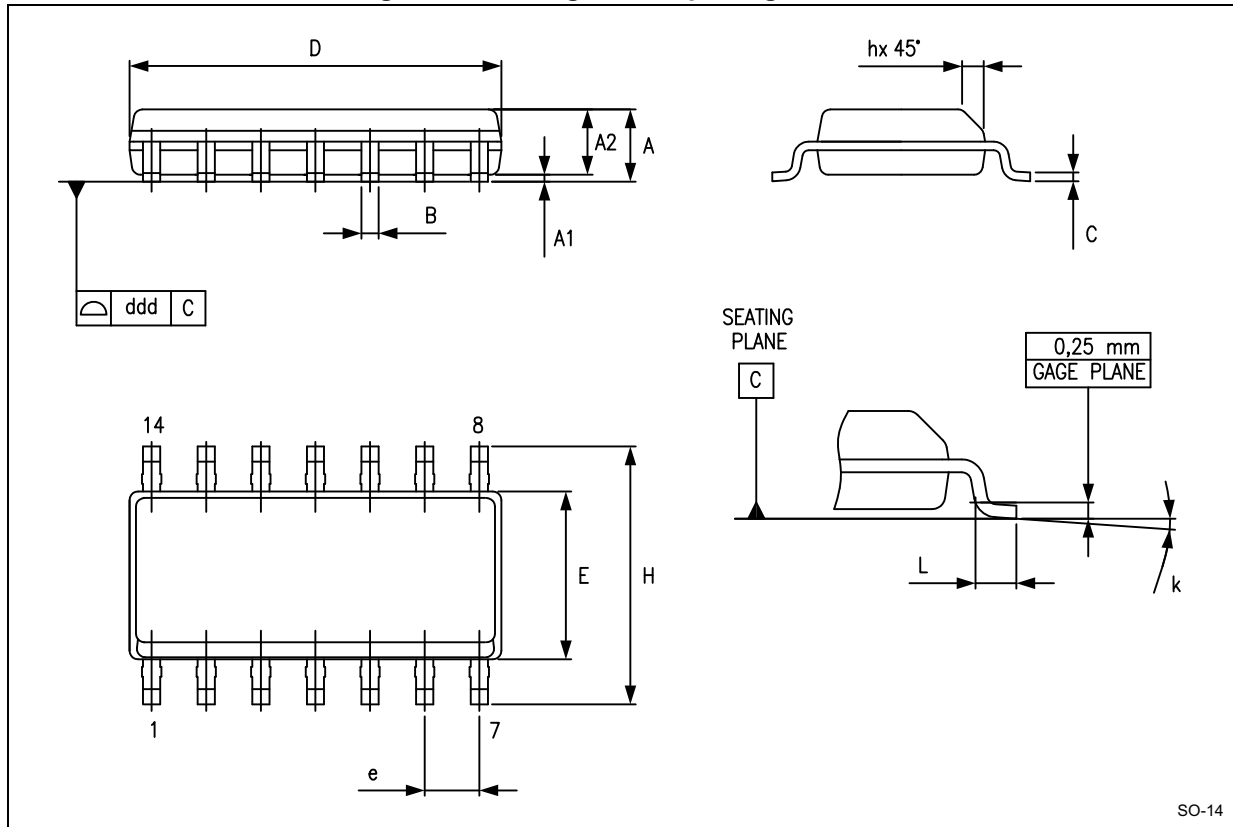


Table 6. SO-14 package mechanical data

| Symbol | Dimensions (mm) | | |
|--------|-----------------|------|------|
| | Min. | Typ. | Max. |
| A | 1.35 | | 1.75 |
| A1 | 0.10 | | 0.25 |
| A2 | 1.10 | | 1.65 |
| B | 0.33 | | 0.51 |
| C | 0.19 | | 0.25 |
| D | 8.55 | | 8.75 |
| E | 3.80 | | 4.00 |
| e | | 1.27 | |
| H | 5.80 | | 6.20 |
| h | 0.25 | | 0.50 |
| L | 0.40 | | 1.27 |
| k | 0 | | 8 |
| ddd | | | 0.10 |

10 Revision history

Table 7. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 08-Mar-2011 | 1 | First release. |
| 21-Sep-2011 | 2 | <ul style="list-style-type: none"> – Updated Table 1 – Minor text changes throughout the document |
| 13-Jun-2013 | 3 | <p>Updated Figure 1, Figure 4 to Figure 7, Figure 9 to Figure 16 (minor corrections).</p> <p>Updated Figure 3 (replaced “VCCmin” by “2 V”).</p> <p>Updated Table 5 (moved “I_{osink}” for “V_{OL1/2/3}” symbols to “Test condition”).</p> <p>Updated Section 5.5 (replaced “Turn-off” by “The two-level turn-off”, added Equation 1).</p> <p>Updated Section 5.6 (added heading for Equation 2).</p> <p>Updated Table 6 (updated data, reversed order of Figure 17 and Table 6).</p> <p>Minor corrections throughout document.</p> |

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